

585 Low Temperature Release Film



Overview: This high gloss elongation release film can be used on wet or prepreg moldings up to 200 degrees F. It is perforated with holes of .045" diameter on 1/2" centers to allow for passage of air and excess resin. This film will hold more resin than the peel ply releases. Not recommended for phenolic systems. 60" wide.

Features & Benefits:

- **Red-tinted, co-polymer, high elongation, low temperature release film with excellent conformability**
- **For use on highly contoured parts**
- **Good release properties in the curing temperature range of most polyesters, vinyl esters and some epoxy, as well as other applications where release films are required**
- **Colored film provides for easy identification and removal from parts**

Physical Properties:

Mechanical Properties	Typical Values
Tensile modulus	<2000
Elongation	>800%

Thermal Properties	°F	°C
Maximum use temperature	250	121
Melt Point (DSC)	318	159

*Values shown above are typical and are not for use as final limiting specifications.